

<b>PCN Number:</b>	20140701000			<b>PCN Date:</b>	07/10/2014
<b>Title:</b>	Qualification of CK5000A Mold Compound in AP1 for PDIP packages				
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Phone:</b>	+1(214)480-6037	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	10/10/2014	<b>Estimated Sample Availability:</b>	Date Provided at Sample request		
<b>Change Type:</b>					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials
				<input type="checkbox"/>	Wafer Fab Process
<b>PCN Details</b>					
<b>Description of Change:</b>					
Texas Instruments Incorporated is announcing the Qualification of CK5000A Mold Compound in Amkor Philippines (AP1) for PDIP packages.					
	<b>Change From:</b>	<b>Change To:</b>			
Mold Compound	DMC2000HG, DMC200NF	CK5000A			
<b>Reason for Change:</b>					
Discontinuation of DMC2000HG & DMC200NF mold compound by Amkor Philippines (AP1).					
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>					
None					
<b>Changes to product identification resulting from this PCN:</b>					
None					
<b>Product Affected:</b>					
ADC0831CCN/NOPB	DS75176BN/NOPB	LM2574HVN-ADJ/NOPB	LM6144BIN/NOPB		
ADC0832CCN/NOPB	DS75176BTN/NOPB	LM2574N-12/NOPB	LM78S40N/NOPB		
ADC0834CCN/NOPB	DS96174CN	LM2574N-3.3/NOPB	LMC6041IN/NOPB		
AM26LS31PC	DS96174CN/NOPB	LM2574N-5.0	LMC6042AIN/NOPB		
DS14C88N	DS96175CN/NOPB	LM2574N-5.0/NOPB	LMC6064IN/NOPB		
DS14C89AN	DS96176CN/NOPB	LM2574N-ADJ/NOPB	LMC6462BIN/NOPB		
DS14C89AN/NOPB	LF353N/NOPB	LM2578AN/NOPB	LMC6464BIN/NOPB		
DS26C31TN	LF398AN/NOPB	LM2671N-5.0/NOPB	LMC6484AIN		
DS26C31TN/NOPB	LF412ACN/NOPB	LM2672N-5.0/NOPB	LMC6484IN		
DS26LS31CN	LF412CN/NOPB	LM2674N-ADJ/NOPB	LMC6484IN/NOPB		
DS26LS31CN/NOPB	LHV720NA/NOPB	LM2675N-ADJ/NOPB	LMC660AIN/NOPB		
DS26LS31N	LM13700N/NOPB	LM2902N/NOPB	LMC660CN/NOPB		
DS3658N	LM2524DN	LM318N	LME49740NA/NOPB		
DS3658N/NOPB	LM2524DN/NOPB	LM318N/NOPB	TP3054N/NOPB		
DS3668N/NOPB	LM2574HVN-12/NOPB	LM319N/NOPB	TP3057N/NOPB		
DS3695N/NOPB	LM2574HVN-15/NOPB	LM331N/NOPB			
DS3695TN/NOPB	LM2574HVN-5.0	LM3578AN/NOPB			
DS485N/NOPB	LM2574HVN-5.0/NOPB	LM386N-1			

## Qualification Report

### PDIP mold compound DMC2000HG discontinuance in AP1 Approved 06/10/2014

#### Product Attributes

Attributes	Qual Device: LF444CN/NOPB	Qual Device: LM319N
<b>Assembly Site</b>	AP1	AP1
<b>Package Family</b>	PDIP	PDIP
<b>Wafer Fab Supplier</b>	GL	GL
<b>Wafer Fab Process</b>	BPBIFET.13.1	BPSLM.8.1

- QBS: Qual By Similarity

#### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LF444CN/NOPB	Qual Device: LM319N
THB	Biased Temperature and Humidity, 85C/85%RH	1000 Hours	-	3/231/0
AC	Autoclave 121C	96 Hours	3/231/0	-
UHAST	Unbiased HAST 130C/85%RH	96 Hours	3/231/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0
HTSL	High Temp Storage Bake 150C	1000 Hours	3/231/0	-

-- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

**Green/Pb-free Status:** Qualified Pb-Free(SMT) and Green

TI Qualification ID: 20130502-84221

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
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Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>